

FLEXIBLE PRINTED CIRCUIT BOARD UNIT CONTRIBUTING TO RELIABLE SOLDERING AND SUPPRESSION OF INCREASED TEM- PERATURE

Abstract

A thermal component is mounted on the front surface of an isolator sheet within a first specific area. A thermally-conductive material is located on the back surface of the isolator sheet on the back of the first specific area. An electrically-conductive material is located on the front surface of the isolator sheet within a second specific area. A thermally-insulating material is located on the back surface of the isolator sheet on the back of the second specific area. The flexible printed circuit board unit of this type allows heat of the thermal component to efficiently radiate from the thermally-conductive material. An increase in temperature can be suppressed in the thermal component. Heat can reliably stay in the electrically-conductive material when a solder material is applied to the surface of the electrically-conductive material. The solder material is allowed to reliably fuse.